

Patent Abstracts of Japan

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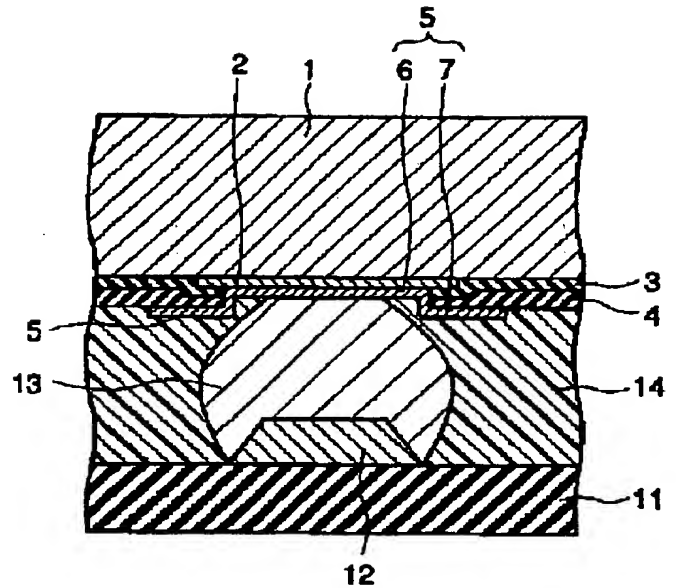
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TITLE : SEMICONDUCTOR DEVICE AND
MANUFACTURE THEREOF



ABSTRACT : **PROBLEM TO BE SOLVED:** To obtain a semiconductor device, having such a structure as to allow a semiconductor substrate with pads arranged at narrow intervals to be mounted on an insulating circuit board, while ensuring insulating properties, and a manufacturing method therefor.

SOLUTION: This semiconductor device comprises an electrode pad 2 formed on a semiconductor substrate 1, a connecting base metal film 5 to be connected to the pad 2, a connecting conductor 13 electrically connected between the film 5 and a terminal electrode 12 on an insulating circuit substrate 11, and a non-conductive resin 14 for covering the region around the conductor 13 and embedding clearances between both the substrates. The film 5 is such, that at least a peripheral region thereof including the outermost edge is not covered with the conductor 13.

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